

Highlights

Excellent Quality and Superior Service

- ▶ Production volumes scheduled in weekly or monthly quantities to meet your needs.
- ▶ Quick Turn
From 4 hours to 5 days
- ▶ Speed time-to-market of new products. Increase market share.
- ▶ QFN's – body sizes from 3 x 3 mm to 12 x 12 mm. Pin counts from 8 to 104. Thickness either .8 or 1.0 mm.
- ▶ BGA – all body sizes, ball configurations and pin counts.
- ▶ Small Outline Plastic Equivalent Packages
- ▶ Ceramic Package Equivalents
- ▶ Pre-Molded Open Cavity Plastic Packages (PM-OCPP)
- ▶ Open Cavity Plastic Packages (OCPP)
- ▶ Experienced Certified Operators
- ▶ Class 1000 Clean room with <Class 100 Laminar Flow Hoods
- ▶ Complete wafer thinning and dicing operations for standard or multi-die type wafers.

CORWIL will assemble your IC devices in plastic packages for production or prototype requirements using transfer mold processes for QFN, BGA and other customer specified package types. QFN and BGA assembly is available in quick-turn prototype or production volumes. Production volumes are scheduled in thousands of units per week to meet your delivery needs.

For the prototype market segment, the Pre-Molded Open Cavity Plastic Package (PM-OCPP) or the OCPP processes provide a quick and inexpensive methodology to satisfy your prototype or sample requirements. The prototype segment also can be addressed with ceramic equivalents to plastic packages. These package options are ideal for customer samples or for de-bugging/engineering builds to quickly check the performance of your new wafer or IC designs in the same type package. All packages offered by CORWIL are assembled under strict quality controls to ensure reliable test data of your devices. Prototype builds available in as fast as 4 hours. This means the **time-to-market** for new products can be **substantially improved** enabling you to **increase market share**. Plastic Package Options include:

- **QFN (Quad Flat No Lead) or DFN (Dual Flat No Lead) Plastic Packages:** QFN's are one of the highest growth packages in the industry. CORWIL produces QFN's in either prototype quantities or production volumes with our transfer mold processes. CORWIL maintains a stock of leadframes for many different body sizes and pin counts. Or, we can create any body size or pin count that meets your specific needs. The total time to design and deliver a new leadframe to your specifications is about two weeks. Assembly turn times are from one day to a five-day standard.
- **Pre-Molded Open Cavity Plastic Package Process (PM-OCPP):** Various pin counts and body sizes are available off-the-shelf for QFN, SOIC, TQFP, SSOP and SOIC with heat sink. After die attach and wire bond, the packages can be left open or sealed with encapsulant or a plastic lid with epoxy preform. 4-hour turn available.
- **Open Cavity Plastic Package Process (OCPP):** CORWIL can prepare your existing plastic packaged devices for assembly with a new die. CORWIL creates a cavity by opening up your existing plastic packages, removing the die and exposing and cleaning the bond pads and paddle. In this prepared package, a new die can be attached and wirebonded into the cavity and sealed with an epoxy encapsulant. You now have an assembled device which can be tested in the exact same equipment used to test production units. After package preparation, assembly turn time is as fast as 4 hours.
- **BGA's:** CORWIL has fine pitch wirebonding with the latest state of the art wire bonders handling pad pitches of 35/70 μm staggered, 45 μm in production, and <45 μm in prototype. CORWIL's flexible process flows can produce all body sizes, all ball configurations and solder ball sizes, and wire counts exceeding 1100 wires per device. CORWIL will use your substrates or will design and manufacture custom substrates to fit your application.
- **Ceramic Package Equivalents:** Ceramic packages replicating plastic packages are ideal for devices which need to be opened for FIB, failure analysis, or engineering tools. Lids can be taped on for easy removal or sealed for high temperature testing.
- CORWIL has built its reputation providing customers with:
excellent quality and superior service

Contact Us At:

CORWIL Technology Corporation
1635 McCarthy Boulevard
Milpitas, CA 95035-7415
Phone: 408-321-6404
Fax: 408-321-6407
E-mail: info@corwil.com
Web: <http://www.corwil.com>



DSCC QML Listed
(Qualified Manufacturers List)
MIL-STD-883 DSCC Suitability